

lines 7-10, delete in their entirety and
substitute therefor --instance, this can be
achieved by exerting the actuating force tending
toward the center of the wafer upon the wafer
peripheral edge.

Page 14, line 17, after "invention," insert --there is
provided a wafer holding device adapted for use in
an apparatus for treating a principal surface of a
semiconductor wafer under a predetermined heating
condition while the back surface of said principal
surface of the wafer is vertically or obliquely
held by the device at the predetermined position
within a chamber of said apparatus. The device
comprises a substrate holder for supporting the
back surface of said wafer thereon and rotating
means for circumferentially rotating said wafer
along with the substrate holder.--;
line 18, change "the" to --the--.

IN THE CLAIMS:

Please amend claim 5 as follows:

5. (Amended) A wafer holding device adapted for use in an
apparatus for treating a principal surface of a semiconductor
wafer under a predetermined heating condition while the back
surface of said principal surface of the wafer is vertically or